

## TRANSMITTAL

Electronic Version v1.1

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<b>Title of Invention</b>	Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking	
Application Number :	10/050507	
Date :	2002-01-16	
First Named Applicant:	Lee Teck	
Confirmation Number:	7687	
Attorney Docket Number:	MTI-31607	
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<b>Documents being submitted:</b>	<b>Files</b>
us-ids	MTI-31607a-usidst.xml us-ids.dtd us-ids.xsl
<b>Comments</b>	